12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260206001.1
Qualify New Assembly Material set for Selected Device(s)
Change Notification / Sample Request

Date: February 06, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260206001.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
UCC28710DR	NULL
UCC28710D	NULL
UCC28631DR	595-UCC28631DR
UCC28711DR	NULL
UCC28740DR	UCC28740DR
UCC28880DR	UCC28880DR
UCC28740D	UCC28740D

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260206001.1	**PCN Date:**	February 06, 2026
Title:	Qualify New Assembly Material set for Selected Device(s)		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	May 07, 2026	**Sample requests accepted until:**	April 07, 2026

***Sample requests received after** April 07, 2026 **will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

	Current	Proposed
Mount compound	4042500	4147858
Mold compound	4212090	4221499

Reason for Change:

Continuity of supply.
Current mount compound being End of life by supplier.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

SN1412008D	UCC28632DR	UCC28711DR	UCC28740D
SN1412008DR	UCC28633D	UCC28712D	UCC28740DR
UCC28630D	UCC28633DR	UCC28712DR	UCC28880D
UCC28630DR	UCC28634D	UCC28713D	UCC28880DR
UCC28631D	UCC28710D	UCC28713DR	
UCC28631DR	UCC28710DR	UCC28720D	
UCC28632D	UCC28711D	UCC28720DR	

Qualification Report

Approve Date 30-JUNE -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	QBS Reference: UCC256604DDBR	QBS Reference: UCC28730DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	3/231/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device UCC28730DR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2506-073

Qualification Report

Approve Date 19-December-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC28730DR	QBS Reference: UCC256604DDBR	QBS Reference: TPSI2140QDWQRQ1	QBS Reference: UCC28730QDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/135/0	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	3/231/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0

Type	#	Test Name	Condition	Duration	Qual Device: UCC28730DR	QBS Reference: UCC256604DDBR	QBS Reference: TPSI2140QDWQRQ1	QBS Reference: UCC28730QDRQ1
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0

- QBS: Qual By Similarity
- Qual Device UCC28730DR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2308-018

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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